

Description

The AP6N10MI uses advanced Trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 100V I_{D} = 6A$

 $R_{DS(ON)}$ < 125m Ω @ V_{GS} =10V (Type: 105m Ω)

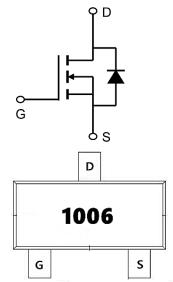
Application

Automative lighting

Load switch

Uninterruptible power supply

Symbol





Rating

Units

Package Marking and Ordering Information

Absolute Maximum Ratings (T_c=25 ℃ unless otherwise noted)

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Product ID	Pack	Marking	Qty(PCS)		
AP6N10MI	SOT23-3L	1006	3000		

 VDS
 Drain-Source Voltage
 100
 V

 VGS
 Gate-Source Voltage
 ± 20 V

 ID@TA=25°C
 Continuous Drain Current, VGS @ 10V1
 6
 A

 ID@TA=70°C
 Continuous Drain Current, VGS @ 10V1
 3.5
 A

 IDM
 Pulsed Drain Current2
 18
 A

Parameter

Ідм	I _{DM} Pulsed Drain Current ²		Α
P _D @T _A =25°C	P _D @T _A =25°C Total Power Dissipation ³		W
Тѕтс	Storage Temperature Range	-55 to 150	℃
TJ	T _J Operating Junction Temperature Range		℃
R _θ JA	R _{θJA} Thermal Resistance Junction-ambient(steady state) ¹		°C/W
Reja	Thermal Resistance Junction-ambient(t<10s) ¹	40	°C/W





Electrical Characteristics (TJ=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100	108		V
Rds(on)	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =4A		105	125	mΩ
NDS(ON)		V _{GS} =4.5V , I _D =2A		120	145	mΩ
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.7	2.5	V
Ipss	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25°C			1	
IDSS		V _{DS} =80V , V _{GS} =0V , T _J =85°C			50	uA
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.3	4.6	Ω
Qg	Total Gate Charge (10V)			3.57		
Qgs	Gate-Source Charge	V _{DS} =30V , V _{GS} =10V , I _D =4A		0.76		nC
Qgd	Gate-Drain Charge			0.71		
Td(on)	Turn-On Delay Time			11		
Tr	Rise Time	V_{DD} =30V , V_{GS} =10V , R_{G} =3.3 Ω		6		20
Td(off)	Turn-Off Delay Time	I _D =1A		30		ns
T _f	Fall Time			4		
Ciss	Input Capacitance			582		
Coss	Output Capacitance	V _{DS} =50V , V _{GS} =0V , f=1MHz		330		pF
Crss	Reverse Transfer Capacitance			36		
ls	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current			2	Α
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2_{\times} The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$
- 3. The power dissipation is limited by 150°C junction temperature
- 4. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.



Typical Characteristics

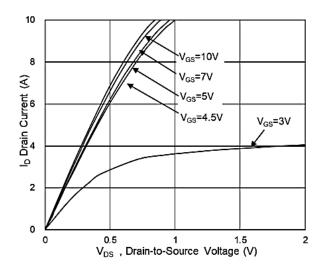


Fig.1 Typical Output Characteristics

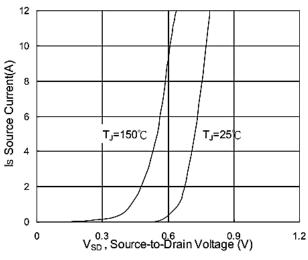


Fig.3 Source Drain Forward Characteristics

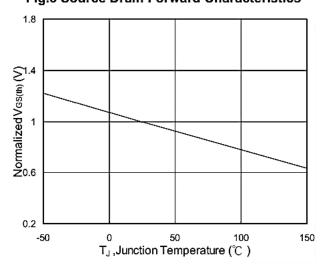


Fig.5 Normalized V_{GS(th)} vs T_J

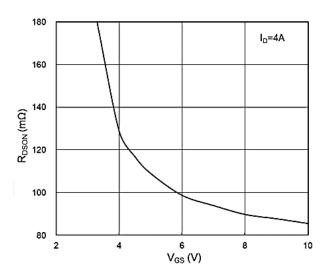


Fig.2 On-Resistance vs G-S Voltage

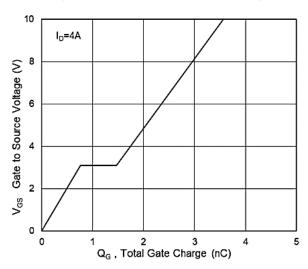


Fig.4 Gate-Charge Characteristics

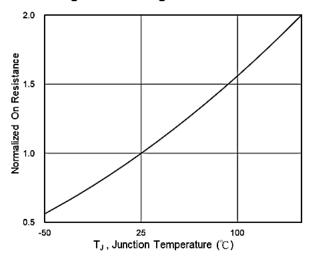
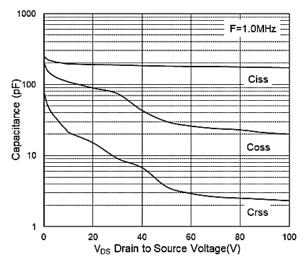


Fig.6 Normalized RDSON vs TJ







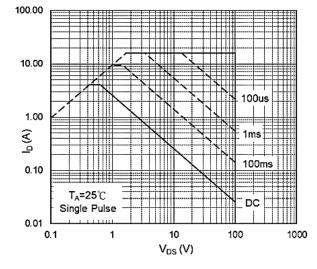


Fig.7 Capacitance

Fig.8 Safe Operating Area

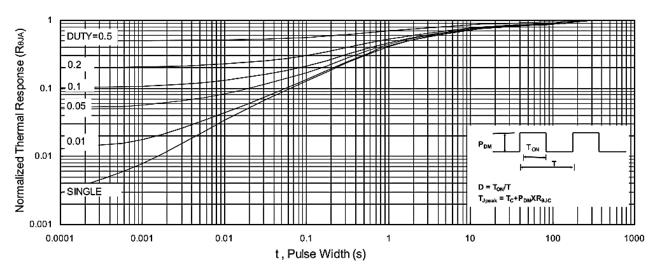
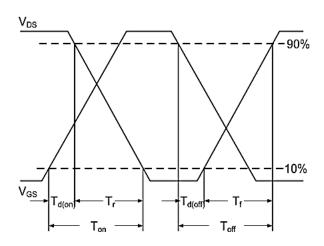
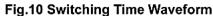


Fig.9 Normalized Maximum Transient Thermal Impedance





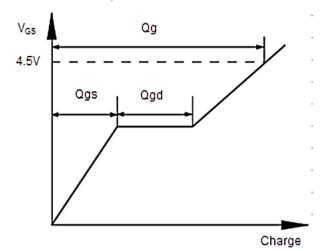
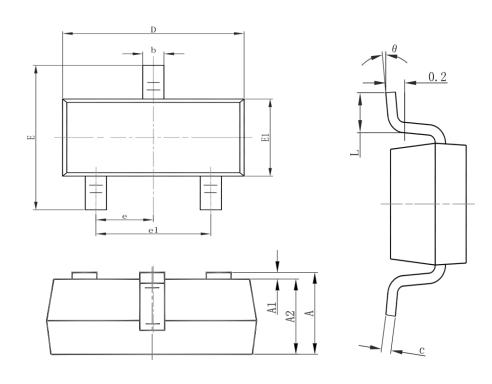


Fig.11 Gate Charge Waveform



Package Mechanical Data-SOT23-3-SLS-Single



Comple al	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
е	0.950	(BSC)	0.03	7(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



100V N-Channel Enhancement Mode MOSFET Attention

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Edition	Date	Change
Rve1.0	2021/8/9	Initial release

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